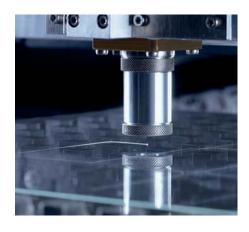


**DLC SERIES**LASER PLATFORMS FOR ELECTRONICS









#### **TECHNICAL SPECIFICATIONS**

#### **DLC SERIES**

Dimensions (L x W x H)	2,900 mm x 2,800 mm x 2,700 mm	
Weight	5,000 - 5,500 kg	
Power supply	200 - 480 V	
Compressed dry air	6 - 7 bar	
Cooling Water	5 - 20 I/min	
Working area	X-axis 1,300 mm Y-axis 1,400 mm up to GEN 5	
Accuracy	$<\pm20\mu\mathrm{m}$ absolute $<\pm10\mu\mathrm{m}$ repeatability	
Available laser sources	Wave length	1,030 nm
	Pulse	ps
Laser spot size	$2\mu\mathrm{m}$	
Beam delivery	Fixed optics	
Safety	CE	

# PROCESS AND SYSTEM VALUES

Material	single glass (unstrengthened and strengthened glass)	
 Material thicknesses	<1.8 mm	
 Sidewall roughness values	$\sim$ 0.4 $\mu$ m	
Maximum product size	up to Gen 5	
Cutting speed	up to 1 m/s	
 Creation of Inner contour	down to 3 mm possible	

## PROCESS AND SYSTEM LIMITATIONS

No coating on top side allowed

For chemically strengthened glass a camera system for alignment detection can be used (25  $\mu$ m accuracy)

## **FEATURES**

- Universal cutting system
- Highly modular system design
- Fast manufacturing
- High volumes and quick ramp-up
- Highly accurate system
- Standalone and line integrable system
- Linear / free forms
- Up to 2 x scanner heads
- Up to 2 x fixed optical process heads

## **OPTIONAL**

- Fully automatic handling (Production)
- Semi-automatic handling (R&D)
- MES interface
- Integrated process metrology
- Import of CAD files (e.g. DXF, DWG)
- Vision system